

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hwa Ja KIM	03/26/2009
Nam Young KIM	03/26/2009
Myung Hee LEE	03/26/2009
Kyoung Bo HAN	03/26/2009
Tae Kwang KIM	03/26/2009
Ji Seop SO	03/26/2009
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEOUL SEMICONDUCTOR CO., LTD.
<b>Street Address:</b>	148-29 Gasan-dong, Geumcheon-gu
<b>City:</b>	Seoul
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>Postal Code:</b>	153-801
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12443314
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<b>NAME OF SUBMITTER:</b>	Hae-Chan Park

OP \$40.00 12443314

Total Attachments: 3

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Approved

SEOUL SEMICONDUCTOR



Attorney's Docket No.: P2779US00

### ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled **LIGHT EMITTING DIODE PACKAGE** ("Application");

upon which United States Letters Patent, Patent Number \_\_\_\_\_, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

**Seoul Semiconductor Co. Ltd.**  
148-29 Gasan-dong, Geumcheon-gu  
Seoul, 153-801  
Republic of Korea

Seoul Semiconductor Co. Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

SEMI. SEMICONDUCTOR



IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Hwa Ja KIM

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First Inventor's Signature:

*Hwa Ja Kim*

Date:

*March 26. 2009*

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Date:

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Third Inventors' Signature:

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*3/26*

SEMICONDUCTOR



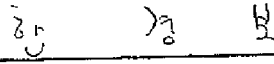
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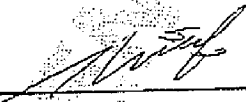
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Sixth Inventor's Signature:

  
\_\_\_\_\_

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※본 문서는 당사의 정보자산이므로, 불법 유출시 관계법과 회사규정에 의해 처벌됩니다.